Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sep 26, 2014 03:10 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
SB130	SB130	DO41-2 (Plastic).csv			PANJIT	**0.336517**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Other	NA	Not Applicable		Not Applicable

* Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration * **4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions** **Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name DO41-2 (Plastic).csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Marking Ink	Other Organic Materials	0.2	Supplier		Aluminum	0.03	7429-90-5	89
			Supplier		Padimate	0.02	21245-01-2	59
			Supplier		Silica	0.01	112945-52-5	30
Plating	Other Nonferrous metals & alloys	4.3	Supplier		Tin	4.3	7440-31-5	12778
Silicon Rubber	Other inorganic materials	5.1	Supplier		Silicon	5.1	7440-21-3	15155
Solder Wafer	Other Nonferrous metals & alloys	1.265	A	Lead/Lead Compounds	Lead	1.17	7439-92-1	3477
			Supplier		Silver	0.032	7440-22-4	94
			Supplier		Tin	0.064	7440-31-5	189
Chip	Other inorganic materials	0.88	Supplier		Silicon	0.88	7440-21-3	2615
Encapsulation	Thermoplastics	123.57	B	Antimony/Antimony Compounds	Antimony Trioxide	2.75	1309-64-4	8172
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	2.75	6386-73-8	8172
			Supplier		Carbon Black	1.37	1333-86-4	4071
			Supplier		Epoxy Resin	20.6	29690-82-2	61215
			Supplier		Silica, vitreous	96.1	60676-86-0	285573
Lead Wire	Other Ferrous alloys, non-stainless steels	201.201	Supplier		Copper	201	7440-50-8	597296
			Supplier		Iron	0.161	7439-89-6	478
			Supplier		Phosphorus	0.04	7723-14-0	119
Marking Ink	Other Organic Materials	0.2	Supplier		2-Propenoic acid polymer	0.13	53192-18-0	386
			Supplier		additive	0.01	947-19-3	30